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**July 2015** 

## FQT7N10L

# N-Channel QFET® MOSFET

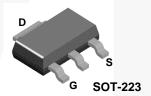
**100 V, 1.7 A, 350 m**Ω

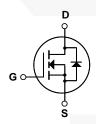
#### **Description**

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

#### **Features**

- 1.7 A, 100 V,  $R_{DS(on)}$ =350 m $\Omega(Max.)$  @ $V_{GS}$ =10 V,  $I_D$ =0.85 A
- Low Gate Charge (Typ. 5.8 nC)
- Low Crss (Typ. 10 pF)
- 100% Avalanche Tested





### **Absolute Maximum Ratings** T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQT7N10L	Unit
V <sub>DSS</sub>	Drain-Source Voltage		100	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>A</sub> = 25°C)		1.7	А
	- Continuous (T <sub>A</sub> = 70	°C)	1.36	А
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	6.8	А
V <sub>GSS</sub>	Gate-Source Voltage		± 20	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	50	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	1.7	А
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	0.2	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns
$P_D$	Power Dissipation (T <sub>A</sub> = 25°C)		2.0	W
	- Derate above 25°C		0.016	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes,		300	°C
۱L	1/8" from case for 5 seconds		300	

#### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		62.5	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$				V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.1		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μΑ
		V <sub>DS</sub> = 80 V, T <sub>C</sub> = 125°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	aracteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.0		2.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 0.85 \text{ A}$ $V_{GS} = 5 \text{ V}, I_D = 0.85 \text{ A}$		0.275 0.300	0.35 0.38	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 0.85 A (Note 4)		2.75		S
C <sub>oss</sub> C <sub>rss</sub>	Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0  MHz		55 12	72 15	pF pF
				12	15	рF
Switch	ing Characteristics					
	Turn-On Delay Time	$V_{DD} = 50 \text{ V}, I_{D} = 7.3 \text{ A},$		9	30	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 50 \text{ V}, I_{D} = 7.3 \text{ A},$ $R_{G} = 25 \Omega$		100	210	ns ns
t <sub>r</sub> t <sub>d(off)</sub>	Turn-On Rise Time Turn-Off Delay Time	$R_G = 25 \Omega$		100	210 45	ns ns
t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	$R_G = 25 \Omega$ (Note 4, 5)		100 17 50	210 45 110	ns ns ns
$t_{r}$ $t_{d(off)}$ $t_{f}$ $Q_{g}$	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge	$R_G = 25 \Omega$ (Note 4, 5) $V_{DS} = 80 \text{ V}, I_D = 7.3 \text{ A},$		100 17 50 4.6	210 45 110 6.0	ns ns ns
t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub>	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge	$R_G = 25 \Omega$ (Note 4, 5) $V_{DS} = 80 \text{ V}, I_D = 7.3 \text{ A}, V_{GS} = 5 \text{ V}$		100 17 50 4.6 1.0	210 45 110 6.0	ns ns ns nC
t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub>	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge	$R_G = 25 \Omega$ (Note 4, 5) $V_{DS} = 80 \text{ V}, I_D = 7.3 \text{ A},$		100 17 50 4.6	210 45 110 6.0	ns ns ns
tr td(off) tf Qg Qgs	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$R_{G} = 25 \ \Omega$ (Note 4, 5) $V_{DS} = 80 \ V, \ I_{D} = 7.3 \ A,$ $V_{GS} = 5 \ V$ (Note 4, 5)		100 17 50 4.6 1.0	210 45 110 6.0	ns ns ns nC
t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge	$R_G = 25~\Omega \label{eq:RG}$ (Note 4, 5) $V_{DS} = 80~V, I_D = 7.3~A, \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 5~V \label{eq:VGS}$ (Note 4, 5)		100 17 50 4.6 1.0	210 45 110 6.0	ns ns ns nC
t <sub>r</sub> t <sub>d(off)</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub> Drain-S	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$R_{G} = 25 \ \Omega$ (Note 4, 5) $V_{DS} = 80 \ V, I_{D} = 7.3 \ A,$ $V_{GS} = 5 \ V$ (Note 4, 5) $N_{GS} = 80 \ V = 100 \ \text{Maximum Ratings}$ ode Forward Current	   	100 17 50 4.6 1.0 2.6	210 45 110 6.0 	ns ns ns nC nC
t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub> Drain-S	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics and Maximum Continuous Drain-Source Diode	$R_{G} = 25 \ \Omega$ (Note 4, 5) $V_{DS} = 80 \ V, I_{D} = 7.3 \ A,$ $V_{GS} = 5 \ V$ (Note 4, 5) $N_{GS} = 80 \ V = 100 \ \text{Maximum Ratings}$ ode Forward Current		100 17 50 4.6 1.0 2.6	210 45 110 6.0  	ns ns ns nC nC
$egin{array}{l} t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ Q_g \\ Q_{gs} \\ Q_{gd} \\ \hline egin{array}{c} \mathbf{Drain-S} \\ I_{S} \\ I_{SM} \\ V_{SD} \\ t_{rr} \\ \hline \end{array}$	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics at Maximum Continuous Drain-Source Diode Maximum Pulsed Drain-Source Diode F	$R_{G} = 25 \ \Omega$ $V_{DS} = 80 \ V, I_{D} = 7.3 \ A,$ $V_{GS} = 5 \ V$ $(Note 4, 5)$ $Note 5$ $Note 6$ $Note 6$ $Note 6$ $Note 7$ $Note 7$ $Note 7$ $Note 7$ $Note 7$ $Note 8$ $Note 8$ $Note 9$		100 17 50 4.6 1.0 2.6	210 45 110 6.0   1.7 6.8	ns ns nc nC nC

- Notes: N

### **Typical Characteristics**

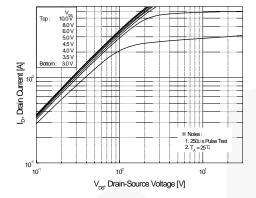


Figure 1. On-Region Characteristics

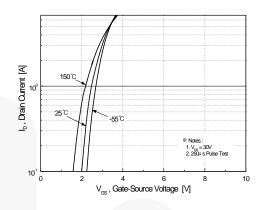


Figure 2. Transfer Characteristics

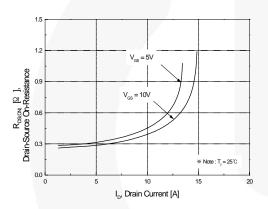


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

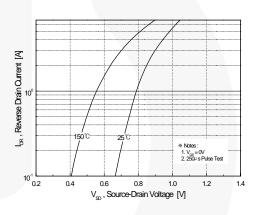


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

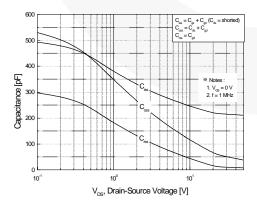


Figure 5. Capacitance Characteristics

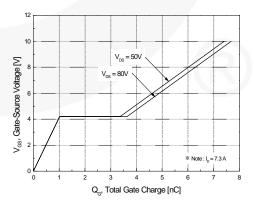
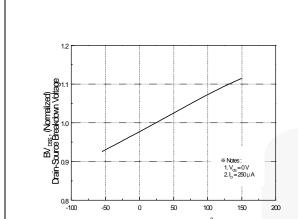
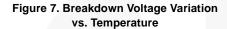


Figure 6. Gate Charge Characteristics



-50

Typical Characteristics (Continued)



T,, Junction Temperature [°C]

150

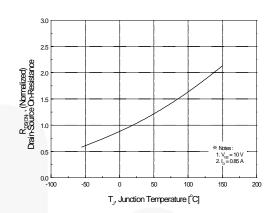


Figure 8. On-Resistance Variation vs. Temperature

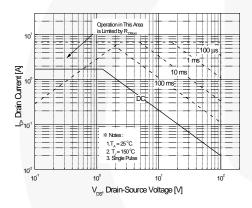


Figure 9. Maximum Safe Operating Area

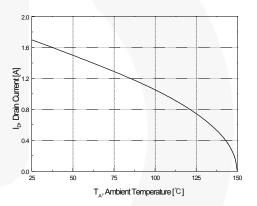


Figure 10. Maximum Drain Current vs. Ambient Temperature

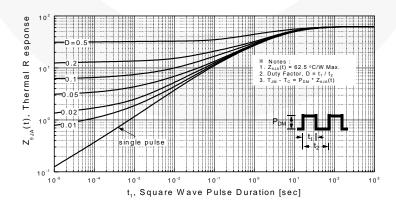
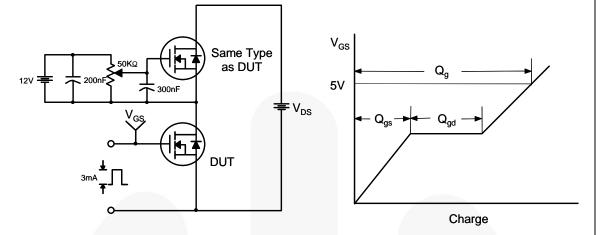
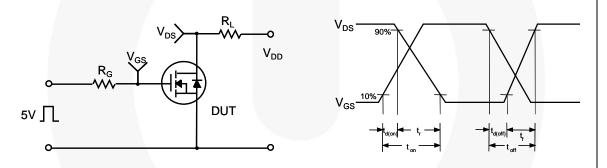


Figure 11. Transient Thermal Response Curve

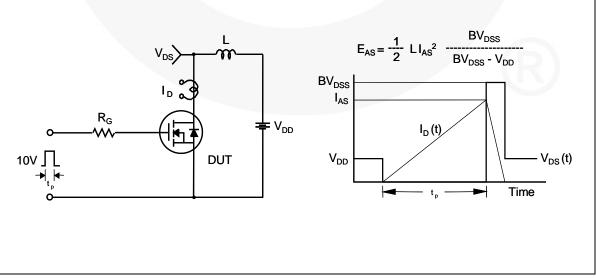
#### **Gate Charge Test Circuit & Waveform**

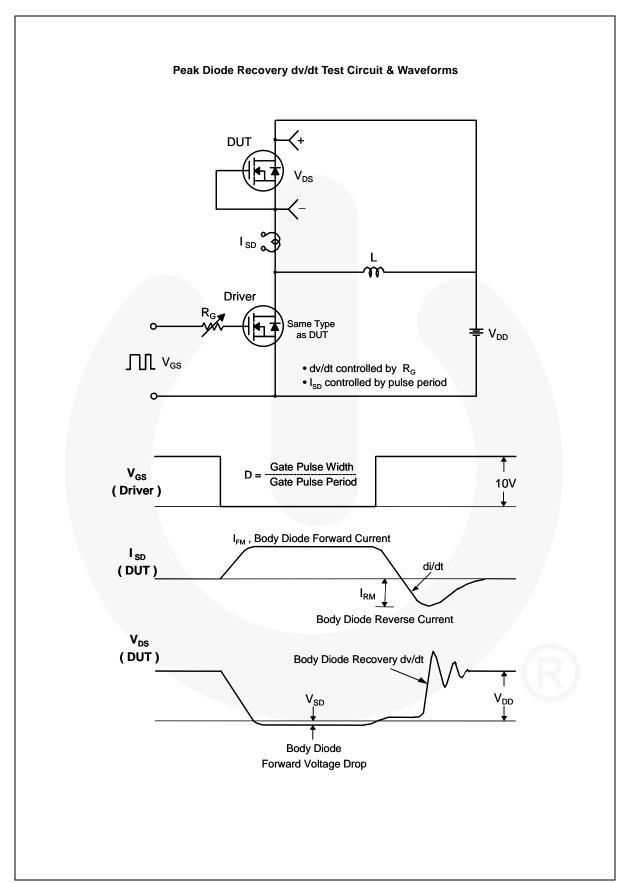


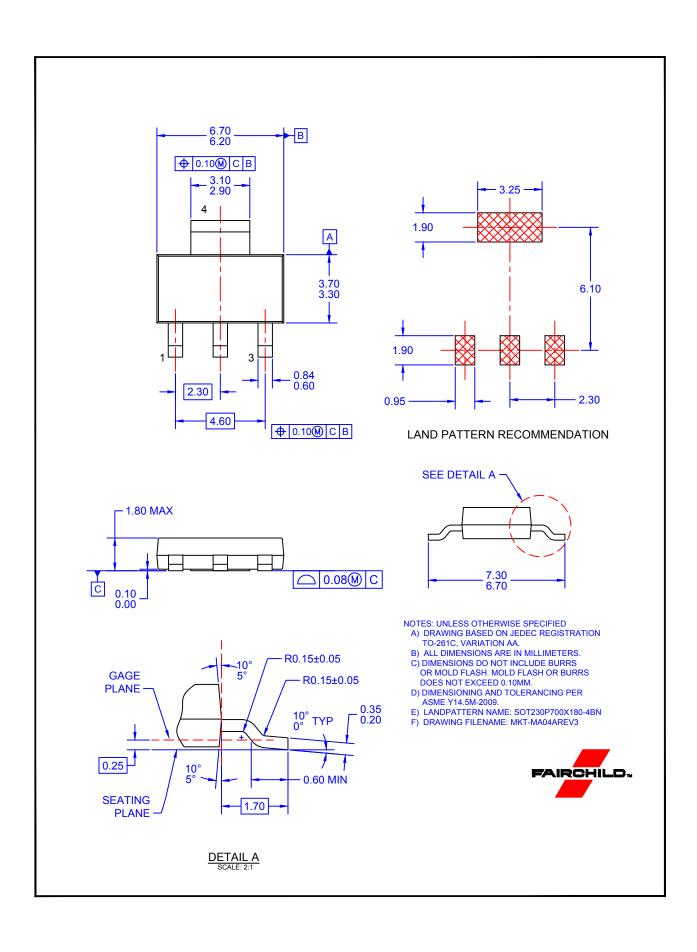
#### **Resistive Switching Test Circuit & Waveforms**



#### **Unclamped Inductive Switching Test Circuit & Waveforms**







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